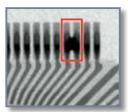


TR7600F2D

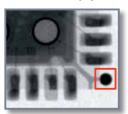
- Inline Ultra-high-resolution Inspection
- Shadow-free Block Scan imaging
- Automated Inspection for High-Mix productions

AUTOMATED
X-RAY INSPECTION

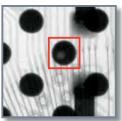
Defect Symptom Images

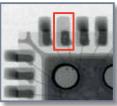


IC Lead Bridging

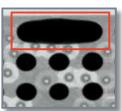


Solder Ball

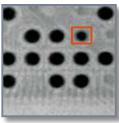




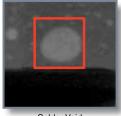
QFN Open



BGA Bridging



BGA Open



Solder Void

Ultimate Image Quality AXI

Focused on delivering the best image quality at top speeds, the TR7600F2D offers a flexible, reliable AXI platform designed for single layer PCB assembly inspection. Smart programming reduces changeover time and operator workload, making the TR7600F2D an ideal solution for high mix productions.

Special Solution for NPI productions

Featuring both automated inline inspection and standalone real-time X-ray imaging, the TR7600F2D is an ideal solution for high mix, low volume productions which require maximum flexibility and high image quality. The powerful hardware platform and flexible imaging options make sure production engineers obtain desired images in minimum time, while delivering high throughput in automated inline mode.

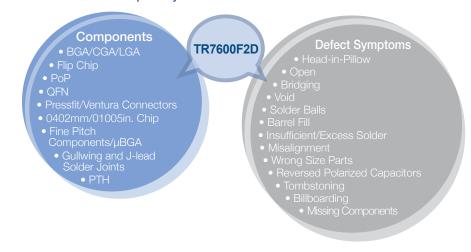
Inline 2.5D Automated X-ray Inspection

- Fast Inline Automated Inspection for Single layer PCBAs
- Ultra-high resolution imaging for ultimate quality at high speed
- Automated Inspection and Pass/Fail Evaluation
- User selectable X-ray power up to 130 kV/300 μA
- Patented 6-axis motion control for maximum flexibility
- Edge-to-edge board inspection up to 900 x 460 mm
- Real-time X-ray view for on-demand inspection

Intelligent Software Solution

- Smart CAD-based or manual programming with auto tuning
- Intelligent detection of solder and assembly defects
- Automatic image quality enhancement
- Automated board warp compensation

Defect Detection Capability



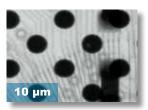
Patented 6-axis Motion Control

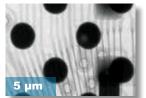
TRI's unique motion control system helps provide clearest images of shielded or overlapping components, enabling reliable automated PCBA inspection and eliminating most shadowing issues.

BlockScan Customized Imaging

BlockScan module enhances the AXI test program coverage by optimizing imaging resolution, overlapping, X-ray power and timing for each FOV. This allows operators to get the best possible image quality and reduces the possibility of false calls on µBGAs, QFNs, and shielded parts.







Multiple Resolutions in One Program

Accurate Inspection Results

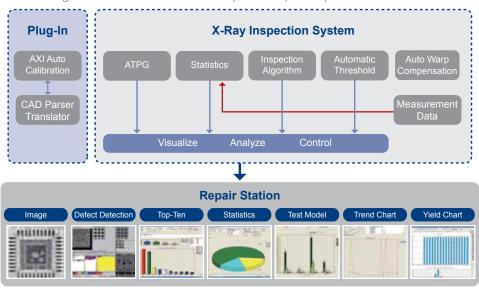
TRI's X-ray systems use intelligent analysis of X-ray data to reliably identify various solder and component defects on a range of components. By combining smart algorithms with ultra-clear imaging quality, the TR7600F2D is designed to provide the most accurate inspection results of BGAs, QFNs, IC lead solder joints and combined Flex-PCB assemblies with microphones and other atypical components.

Radiation Safe Design

Designed with safety in mind, TRI's AXI systems have full lead shielding which prevents harmful exposure in everyday use and reduces X-ray leakage below background radiation levels of 0.5 µSv/hr. The certified safety design conforms to USFDA Code of Federal Regulations Title 21, Part 1020.40.

Repair Station

The TR7600F2D collects a wide range of inspection data to offer instantaneous process monitoring and analysis. This integrated approach offers clear statistical feedback that improves defect management and enhances the efficiency of the inspection process.



Yield Management System 4.0

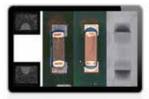
YMS 4.0 provides a M2M centralized inspection monitoring and remote access fine tuning throughout the SMT line. Built-in support for SPI, AOI, AXI and ICT systems helps track Alarms and SPC data to simplify production quality monitoring. YMS 4.0 is TRI's Industry 4.0 closed loop software to assure your production line Inspection quality and efficiency.



The Yield Management System allows operators to aggregate information from individual TRI inspection systems for statistical analysis of production line defect rates, reviewing and fine-tuning inspection results, and identifying component defect trends and emerging production issues.



PRODUCTION ANALYSIS

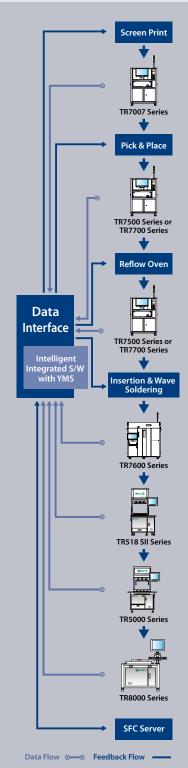


CENTRALIZED
INSPECTION CENTER



REAL TIME SPC TREND

Yield Management System



Inspection results and data integration

- Real time SPC and production yield management
- · Quality reports and close loop tracking
- Support defect component analysis and improvements
- Knowledge Management (KM)
- Productivity and Quality Management

SPECIFICATIONS

X-Ray & Imaging System

X-ray Source	130 kV max (user adjustable)
Image Resolutions	5 μm,10 μm, 15 μm (factory setting)
Camera	High resolution flat panel camera

Inspection Functions

Component Level Defects	Missing, Misalignment, Tombstoning, Billboarding, Tantalum Polarity, Rotation
Joint Level Defects	Insufficient Solder, Excess Solder, Bridging, Open, Solder Ball, Non-wetting, Void, Lifted Lead

X-Y Table & Control

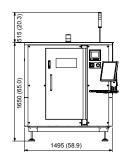
High-precision ball screw/servo motor with DSP-based motion controller

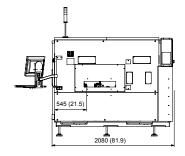
PCB & Conveyor System

Max. PCB Size	900 x 460 mm (35.4 x 18.1 in.)
PCB Thickness	0.6 - 5 mm
PCB Transport Height	880 – 920 mm (34.6 – 36.2 in.)*
Max. PCB Weight	3 kg (7 lbs) [8 kg (18 lbs) optional]
PCB Carrier/Fixing	Motor Driven/Clamping
Clearance	
Top 15 µm	30 mm (1.18 in.)
10 μm	20 mm (0.79 in.)
5 μm	10 mm (0.39 in.)
Bottom	40 mm (1.58 in.)
Edge	3 mm (0.11 in.)

^{*} SMEMA Compatible

Dimensions





Unit: mm (in.)

Weight	3250 kg (7165 lbs)
Power Requirement	200 – 240 VAC single phase,
	50/60 Hz, 4 kVA
Air Requirement	72 psi – 87 psi (5 – 6 bar)

Optional Accessories

Barcode Scanner, Repair Station, Offline Editor & Yield Management System (YMS 4.0)

TRI has a patent in System and Method for Laminography Inspection

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TRI * 德律 * TRI INNOVATION *

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